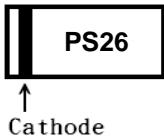


RoHS Compliant Product
A suffix of "-C" specifies halogen-free

FEATURES

- Heatsink Structure
- Low Profile, Typical Thickness 0.8mm
- Low Forward Voltage Drop
- Super Low V_F Schottky Barrier Diodes
- Moisture Sensitivity: Level 1, per J-STD-020
- High Temperature Soldering Guaranteed: 260°C/10 seconds

MARKING



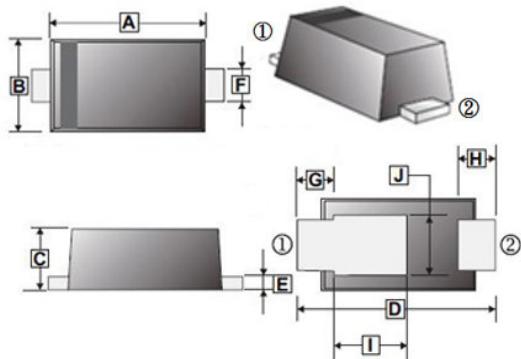
PACKAGE INFORMATION

Package	MPQ	Leader Size
SOD-123DT	3K	7 inch

ORDER INFORMATION

Part Number	Type
SM260DT-C	Lead (Pb)-free and Halogen-free

SOD-123DT



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.90	3.10	F	0.85	1.05
B	1.90	2.10	G	0.60	REF.
C	0.75	0.90	H	0.40	0.85
D	3.50	3.90	I	1.66	REF.
E	0.10	0.25	J	1.30	1.70



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	60	V
Maximum RMS Voltage	V_{RMS}	42	V
Maximum DC Blocking Voltage	V_{DC}	60	V
Maximum Average Forward Rectified Current	I_F	2	A
Peak Forward Surge Current @8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	50	A
Rating for Fusing ($t < 8.3\text{ms}$)	I^2t	10	A^2s
Maximum Instantaneous Forward Voltage @ $I_F=2\text{A}$	V_F	0.65	V
		0.58	
Maximum DC Reverse Current @ Rated DC Blocking Voltage	I_R	50	μA
		15	mA
Typical Junction Capacitance ³	C_J	95	pF
Typical Thermal Resistance from Junction-Ambient ¹	$R_{\theta JA}$	60	$^\circ\text{C/W}$
Typical Thermal Resistance from Junction-Case ²	$R_{\theta JC}$	28	
Typical Thermal Resistance from Junction-Lead ¹	$R_{\theta JL}$	6	
Operating Junction and Storage Temperature	T_J, T_{STG}	-55~150	$^\circ\text{C}$

Notes:

1. The thermal resistance from junction-ambient or lead, mounted on P.C.B with 5x5mm copper pads, 2oz, FR-4 PCB.
2. The thermal resistance from junction-case, mounted on P.C.B with recommended copper pads, 2oz, FR-4 PCB.
3. Measured at 1MHz and applied reverse voltage of 4V D.C.

CHARACTERISTIC CURVES

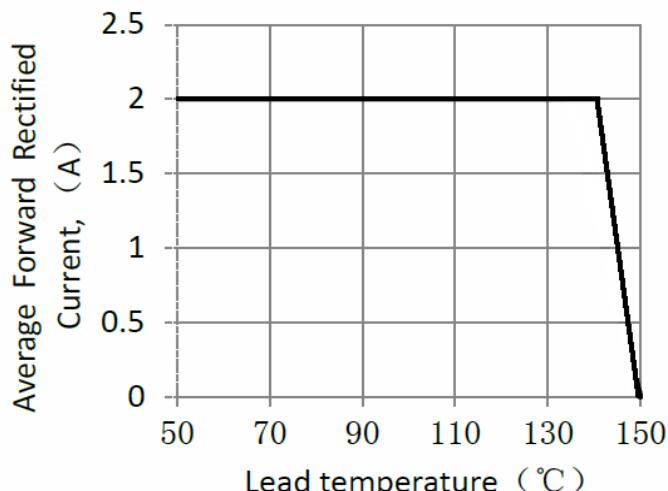


Figure 1. Forward Current Derating Curve

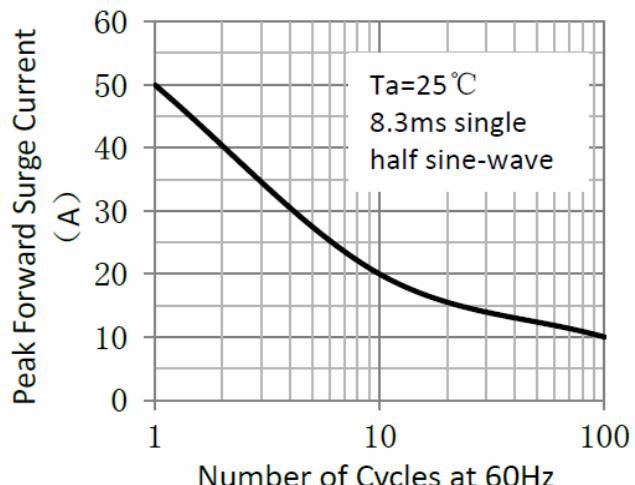


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

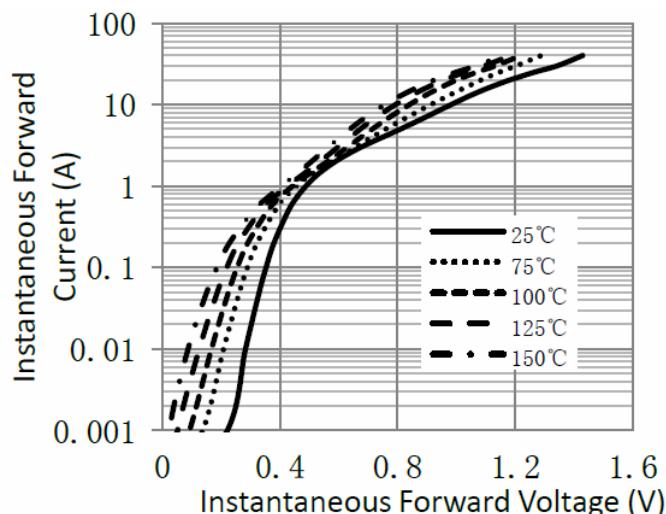


Figure 3. Typical Instantaneous Forward Characteristics

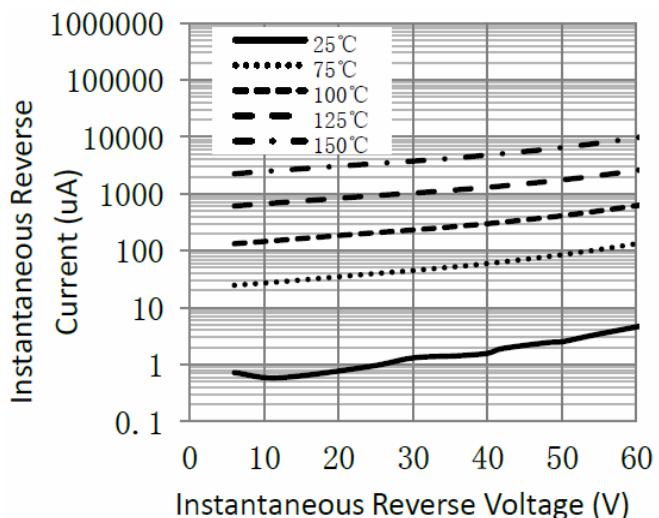


Figure 4. Typical Reverse Characteristics

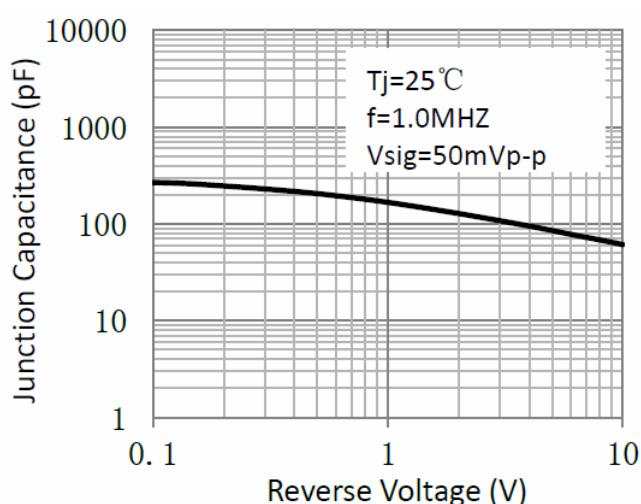
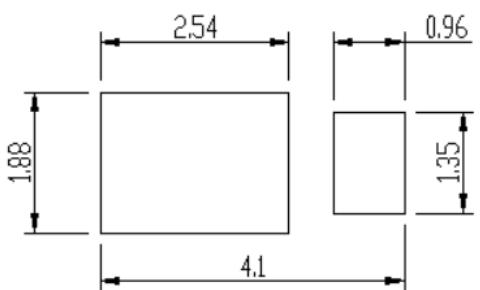


Figure 5. Typical Junction Capacitance



*Dimensions in millimeters

Figure 6. Mounting Pad Layout